# Point and Line Defects: Defects in crystals

#### 0-dimensional: point defects

- vacancy (missing atom)
- self-interstitial (extra atom, off lattice site)
- impurity, substitutional or interstitial
- antisite defects in ordered alloy (e.g., As on Ga site in GaAs)
- conduction electron or hole in semiconductor
- complexes formed from above defects

   (e.g., solute-vacancy pair, color center,
   Frenkel pair, Schottky defect, ...)
- 2-dimensional: planar defects
- boundary: grain-, twin, interphase
- antiphase boundary
- stacking fault

#### 1-dimensional: line defects

- dislocation, perfect
- dislocation, partial
- boundary dislocation
- disconnection
- loop formed by vacancies or self-interstitials
- specialized defect: {311}-Si defects

#### 3-dimensional: volumetric defects

- precipitate
- void
- stacking-fault tetrahedron

Our focus: point and line defects, their interaction, and with other higher dimensional defects

### Material properties governed by defects

electronic and transport properties

- resistivity / conductivity
- (ion) diffusion
- photo emission
- transparency / photoadsorption
- superconductivity

### mechanical properties

- strength
- ductility
- toughness
- corrosion resistance

#### structural properties

- crystal growth
- grain size
- recrystallization mechanism
- phase transformations

### **Defect properties**

structural: where are the atoms, relative to the perfect crystal?

tic displacements)

lative to the perfect crystal?

chemical: participation in reactions

- , positrons, neutrons)
  - scattering cross-section? cause of contrast in microscopy?

thermodynamic: formation energy/enthalpy/entropy

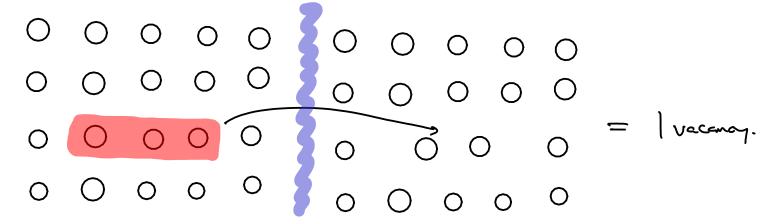
- equilibrium (local or global) concentration
- interaction between defects
- migration of defects

Primary focus: structural, electronic, thermodynamics properties

### Exemple: Pont Defect Proporties

Start'simple": vocancy = remove at an from corrected

Structure? Remove another, yes? Multiple approaches. Take I at not. Replace 2 (neighboring) at my with I. Etc.... Anything that goes from N to all atoms is a vaccinar



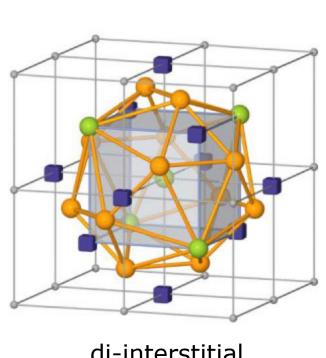
But also note: even mour simple case where we remove one stum, neighborry atom will "relear" (displace

Suggest ve may want a way to unambiguously define the "size" of a point defect to differentiate these structural differences

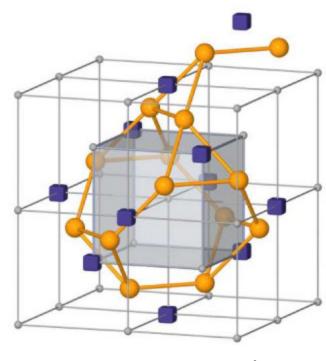
Car dis note similar arguments for interstitids. Classic exemple: Cravdian where NHI atoms in a row replace N atoms.

## Unusual defect structures: Iron

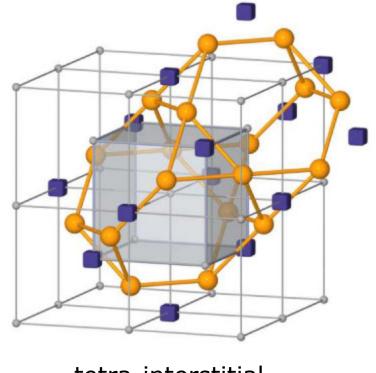
di-interstitial structure = 12 self-interstitials + 10 vacancies



di-interstitial



tri-interstitial



tetra-interstitial

blue squares = vacancies orange atoms = self-interstitials

MC Marinica et al. Phys. Rev. Lett. 108, 025501 (2012)

But there are other properties to consider (even for o	ur humble rocanay)!
- electronic: cherge? If we make a vacaray in Ne	
requires compensation of charge	
- electronic: defect levels? In a Semiconductor, the charge state of a defect depends in the Ferni level	
(can correspond to an electronic state in the landudin	
defeat charge state	confets stracture of defect too!  lefect with an extra e (or a hole) may even  reak symmetry in a different way.  techniques like EPR ere sensitive to this change)

### Thermodynamic properties

- Basic question for point défects: how many are present? De pards on equilibrium vs. non-equilibrium.

Changing conditions change what defines equilibrium (and this can be some than just change in T)

Es: vocancies have an equilibrium concentration  $C_v^o(T) = e^{-G_v^t/k_BT}$  (Archerium form) So as TL,  $C_v^o L$ 

But that equilibran value may be smaller than the current concentration — and adjustment requires elimination of vacancies at sinks. If sinks are not available — concentration is locally formen in place — this may drive defect reactions, like two reconcies forming a directory

Note also that the conditions for equilibrium can very spatially, as it depends on more than just T.

Ex: strem. Equil vacancy (and self-interstitied) concentration depends on strem, and strem is often spatially betweeneas (in part, due to defects)

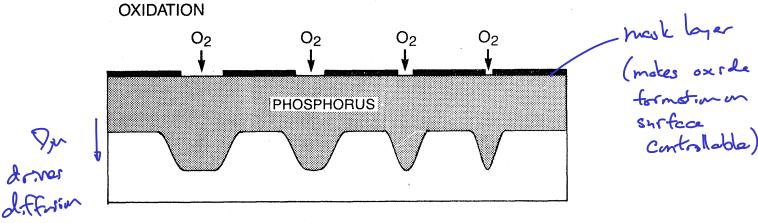
-> we can see this in properties that depud in defeat concentration, like deffusion.

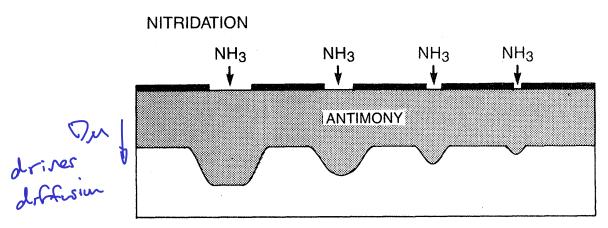
## Oxide-enhanced diffusion

Injection of self-interstitials and vacancies affects diffusion

Free surfaces also act as
Sources i simbs for vacancies
and interstituds, making it
exister to produce equil.
Conditions

INTERFACE KINETICS





PM Fahey et al., Rev. Mod. Phys. 61, 289 (1989)

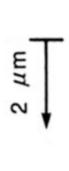
# Oxide-enhanced diffusion

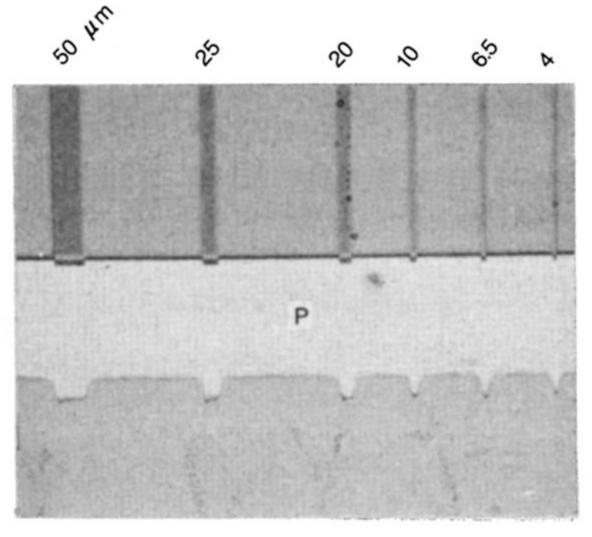
Oxide layer injects self-interstitials into bulk

local expansion at the surface due to lattice mismatch between oxide and 5.

- more interstitions below the exide.

P diffusion occur via kick-ont m S: - dependent on sett-interation Concentration





4h at 1100 C

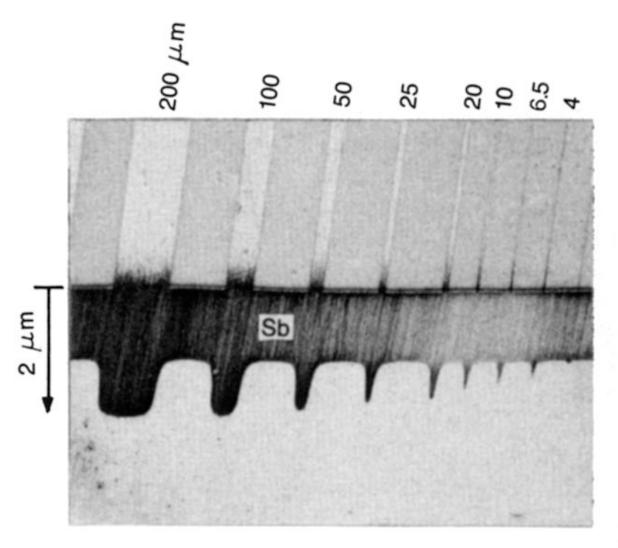
## Oxide-enhanced diffusion

Nitride layer injects vacancies into bulk

local compression at the surface due to lattice mismatch between nitride and Si

more vecancres below the not ride

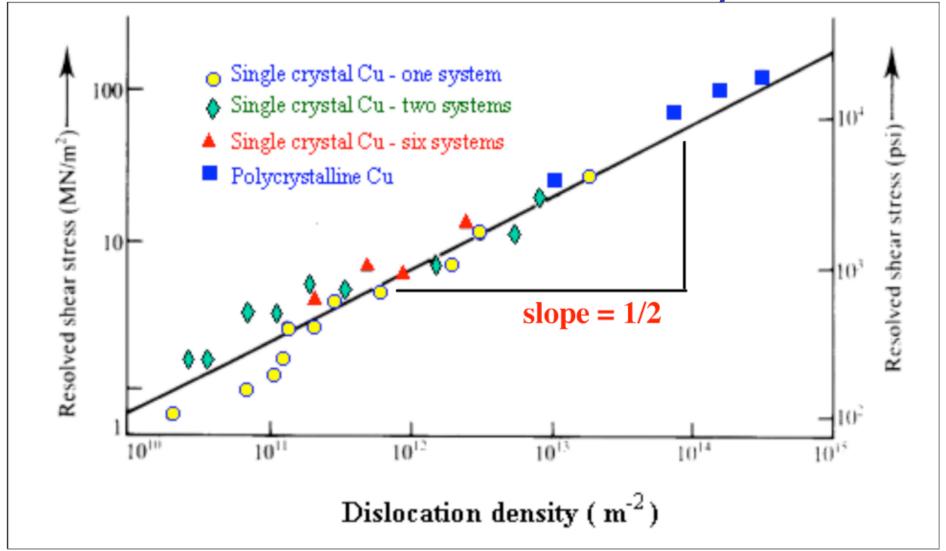
Sto diffusion occurs VI- a vaconcymediated mechanism -> dependent on vaconcy concentration



1h at 1100 C

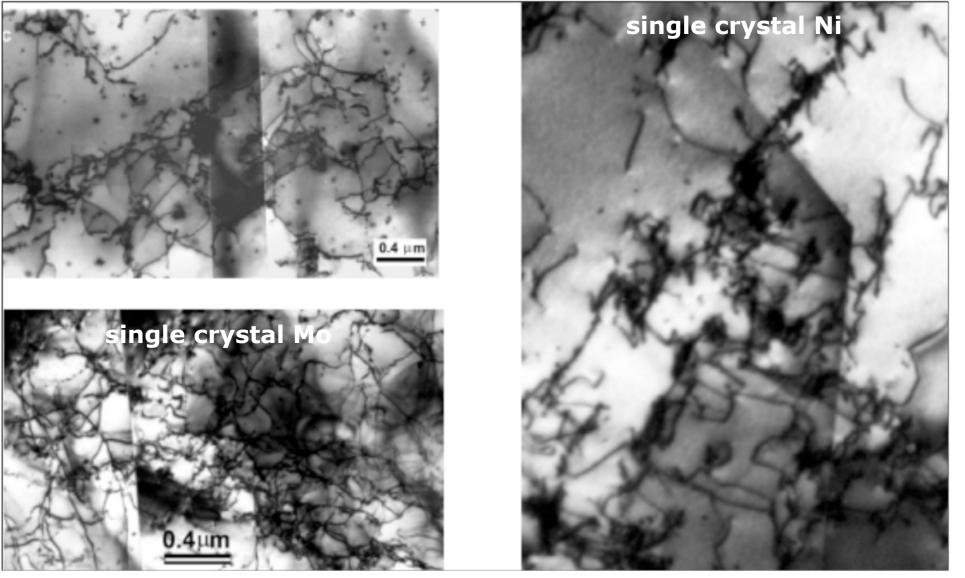
Cu CRSS vs. dislocation density

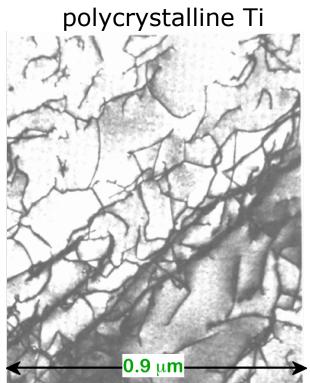
Plastic deformation in metals promerily through motion of dislocations (1) 1/1 interections make I density ? and requires higher stress to more I = work hardening.



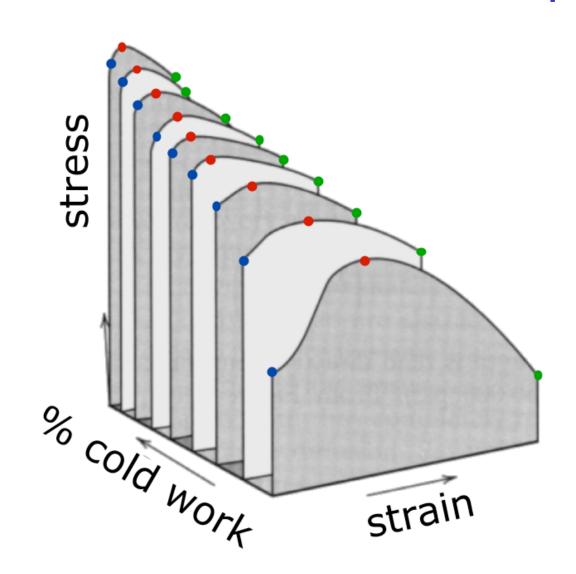
adapted from H Weidersich, J. Metals 16, 425 (1964)

# Cold work microstructure





# Effect of repeated cold work



repeated wire-drawing: raises yield stress raises tensile stress lowers ductility

all due to persistent dislocation microstructure